

L Number	Hits	Search Text	DB	Time stamp
1	998	inspect\$4 with (holes or openings) with (wafer or sample or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/30 01:23
2	254	(inspect\$4 with (holes or openings) with (wafer or sample or semiconductor)) and (charged-particle or (charged adj particle) or electron)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/30 01:23
3	3	((inspect\$4 with (holes or openings) with (wafer or sample or semiconductor)) and (charged-particle or (charged adj particle) or electron)) and ((detect\$5 or measur\$6) near4 current with (sample or wafer) with ground)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/30 01:25
5	2	((((inspect\$4 with (holes or openings) with (wafer or sample or semiconductor)) and (charged-particle or (charged adj particle) or electron)) and ((detect\$5 or measur\$6) near4 current with (sample or wafer) with ground)) and (current near4 (distribution or spectrum or graph\$3))) and bright\$5 and (display\$3 or map\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/30 01:27
4	3	((inspect\$4 with (holes or openings) with (wafer or sample or semiconductor)) and (charged-particle or (charged adj particle) or electron)) and ((detect\$5 or measur\$6) near4 current with (sample or wafer) with ground)) and (current near4 (distribution or spectrum or graph\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/30 01:42
6	2	"6559662"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/30 01:42
7	1		USPAT	2003/11/30 01:46
8	1		USPAT	2003/11/30 01:47
9	1		USPAT	2003/11/30 01:48
10	1		USPAT	2003/11/30 01:49
11	1		USPAT	2003/11/30 01:50
12	1		USPAT	2003/11/30 01:50
13	1		USPAT	2003/11/30 01:51
14	1		USPAT	2003/11/30 01:51
15	1		USPAT	2003/11/30 01:52
16	1		USPAT	2003/11/30 01:52
17	1		USPAT	2003/11/30 01:54
18	1		USPAT	2003/11/30 01:54